

MP4203

HIGH POWER SWITCHING APPLICATIONS

HAMMER DRIVE, PULSE MOTOR DRIVE AND INDUCTIVE LOAD SWITCHING

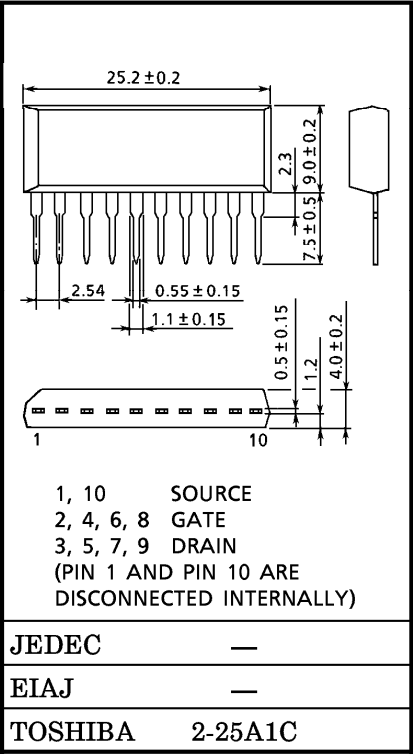
- 4V Gate Drive Available
- Small Package by Full Molding (SIP 10 Pin)
- High Collector Power Dissipation (4 Devices Operation)  
: P<sub>T</sub>=4W (Ta=25°C)
- Low Drain-Source ON Resistance : R<sub>DS (ON)</sub>=0.3Ω (Typ.)
- Low Leakage Current : I<sub>GSS</sub>= ±10μA (Max.) (V<sub>GS</sub>= ±16V)  
I<sub>DSS</sub>= -100μA (Max.) (V<sub>DS</sub>= -60V)
- Enhancement-Mode : V<sub>th</sub>= -0.8~-2.0V (I<sub>D</sub>= -1mA)

MAXIMUM RATINGS (Ta = 25°C)

| CHARACTERISTIC                                   | SYMBOL           | RATING  | UNIT |
|--------------------------------------------------|------------------|---------|------|
| Drain-Source Voltage                             | V <sub>DSS</sub> | -60     | V    |
| Gate-Source Voltage                              | V <sub>GSS</sub> | ±20     | V    |
| Drain Current                                    | I <sub>D</sub>   | -5      | A    |
| Peak Drain Current                               | I <sub>DP</sub>  | -10     | A    |
| Drain Power Dissipation<br>(1 Device Operation)  | P <sub>D</sub>   | 2.0     | W    |
| Drain Power Dissipation<br>(4 Devices Operation) | P <sub>DT</sub>  | 4.0     | W    |
| Chennel Temperature                              | T <sub>ch</sub>  | 150     | °C   |
| Storage Temperature Range                        | T <sub>stg</sub> | -55~150 | °C   |

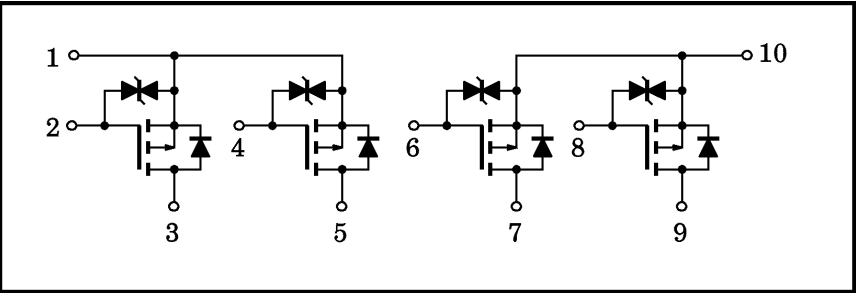
INDUSTRIAL APPLICATIONS

Unit in mm



Weight : 2.1g (Typ.)

ARRAY CONFIGURATION

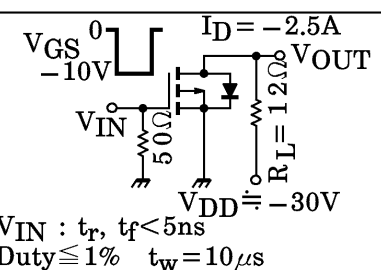


## THERMAL CHARACTERISTICS

| CHARACTERISTIC                                                                             | SYMBOL                | MAX. | UNIT                      |
|--------------------------------------------------------------------------------------------|-----------------------|------|---------------------------|
| Thermal Resistance of Channel to Ambient<br>(4 Devices Operation, $T_a=25^\circ\text{C}$ ) | $\Sigma R_{th(ch-a)}$ | 31.2 | $^\circ\text{C}/\text{W}$ |
| Maximum Lead Temperature for Soldering Purposes<br>(3.2mm from Case for 10s)               | $T_L$                 | 260  | $^\circ\text{C}$          |

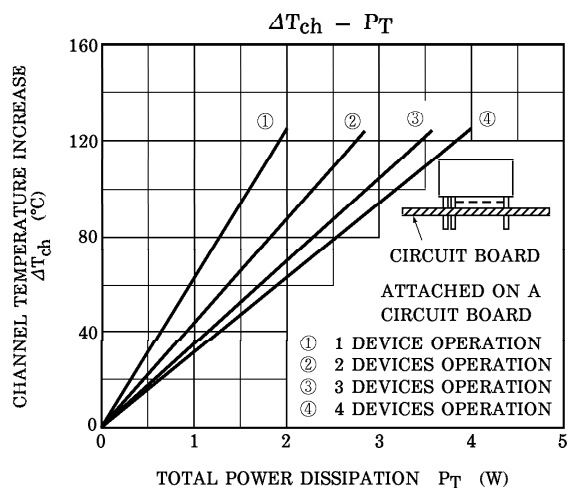
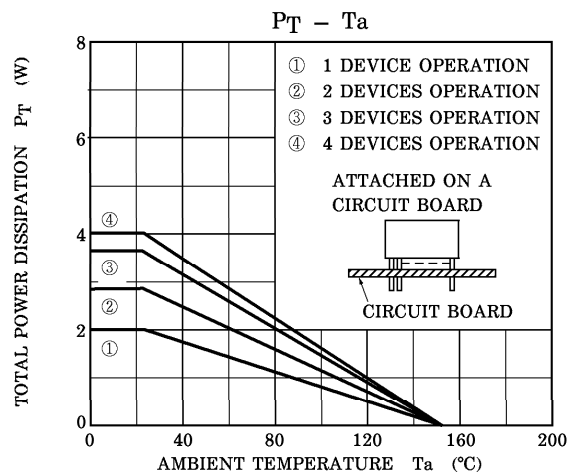
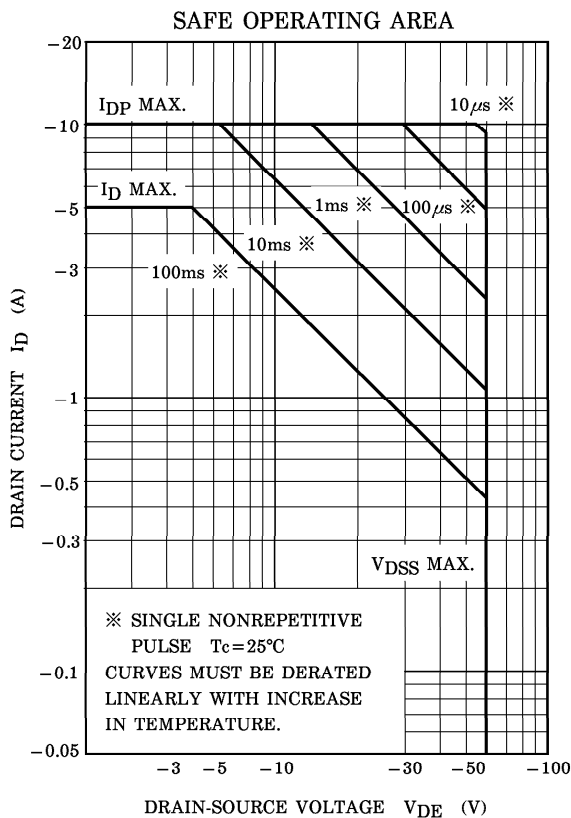
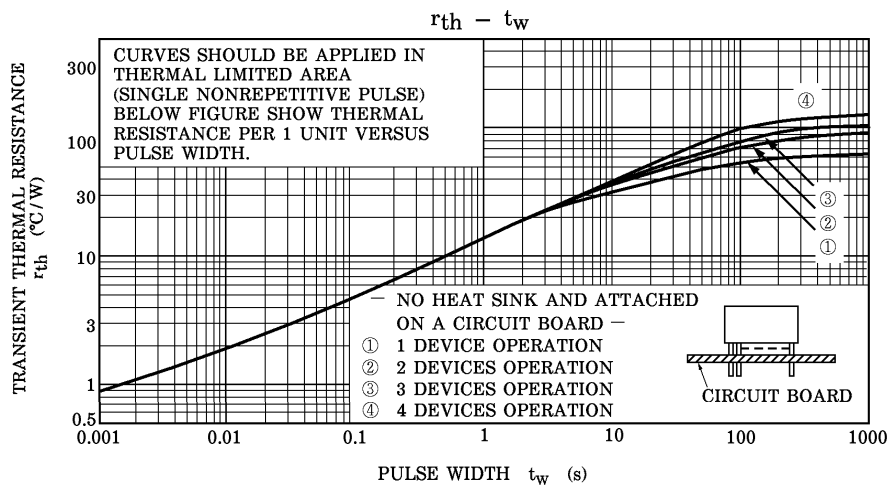
This Transistor is an Electrostatic Sensitive Device. Please Handle with Caution.

ELECTRICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

| CHARACTERISTIC                                     |               | SYMBOL        | TEST CONDITION                                                                       | MIN. | TYP. | MAX.     | UNIT          |
|----------------------------------------------------|---------------|---------------|--------------------------------------------------------------------------------------|------|------|----------|---------------|
| Gate Leakage Current                               |               | $I_{GSS}$     | $V_{GS} = \pm 16\text{V}$ , $V_{DS} = 0$                                             | —    | —    | $\pm 10$ | $\mu\text{A}$ |
| Drain Cut-off Current                              |               | $I_{DSS}$     | $V_{DS} = -60\text{V}$ , $V_{GS} = 0$                                                | —    | —    | -100     | $\mu\text{A}$ |
| Drain-Source Breakdown Voltage                     |               | $V_{(BR)DSS}$ | $I_D = -10\text{mA}$ , $V_{GS} = 0$                                                  | -60  | —    | —        | V             |
| Gate Threshold Voltage                             |               | $V_{th}$      | $V_{DS} = -10\text{V}$ , $I_D = -1\text{mA}$                                         | -0.8 | —    | -2.0     | V             |
| Drain-Source ON Resistance                         |               | $R_{DS(ON)}$  | $V_{GS} = -4\text{V}$ , $I_D = -2.5\text{A}$                                         | —    | 0.45 | 0.8      | $\Omega$      |
|                                                    |               |               | $V_{GS} = -10\text{V}$ , $I_D = -2.5\text{A}$                                        | —    | 0.30 | 0.4      |               |
| Forward Transfer Admittance                        |               | $ Y_{fs} $    | $V_{DS} = -10\text{V}$ , $I_D = -2.5\text{A}$                                        | 1.0  | 2.0  | —        | S             |
| Input Capacitance                                  |               | $C_{iss}$     | $V_{DS} = -10\text{V}$ , $V_{GS} = 0$ , $f = 1\text{MHz}$                            | —    | 380  | —        | pF            |
| Reverse Transfer Capacitance                       |               | $C_{rss}$     |                                                                                      | —    | 90   | —        |               |
| Output Capacitance                                 |               | $C_{oss}$     |                                                                                      | —    | 270  | —        |               |
| Switching Time                                     | Rise Time     | $t_r$         |  | —    | 30   | —        | ns            |
|                                                    | Turn-on Time  | $t_{on}$      |                                                                                      | —    | 50   | —        |               |
|                                                    | Fall Time     | $t_f$         |                                                                                      | —    | 48   | —        |               |
|                                                    | Turn-off Time | $t_{off}$     |                                                                                      | —    | 120  | —        |               |
| Total Gate Charge<br>(Gate-Source Plus Gate-Drain) |               | $Q_g$         | $V_{DD} = -48\text{V}$ , $V_{GS} = -10\text{V}$ ,<br>$I_D = -5\text{A}$              | —    | 20   | —        | nC            |
| Gate-Source Charge                                 |               | $Q_{gs}$      |                                                                                      | —    | 12   | —        |               |
| Gate-Drain ("Miller") Charge                       |               | $Q_{gd}$      |                                                                                      | —    | 8    | —        |               |

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

| CHARACTERISTIC             | SYMBOL    | TEST CONDITION                         | MIN. | TYP. | MAX. | UNIT          |
|----------------------------|-----------|----------------------------------------|------|------|------|---------------|
| Drain Reverse Current      | $I_{DR}$  | —                                      | —    | —    | -5   | A             |
| Peak Drain Reverse Current | $I_{DRP}$ | —                                      | —    | —    | -10  | A             |
| Diode Forward Voltage      | $V_{DSF}$ | $I_{DR} = -5\text{A}$ , $V_{GS} = 0$   | —    | 1.0  | 1.6  | V             |
| Reverse Recovery Time      | $t_{rr}$  | $I_{DR} = -5\text{A}$ , $V_{GS} = 0$   | —    | 170  | —    | ns            |
| Reverse Recovery Charge    | $Q_{rr}$  | $dI_{DR}/dt = -20\text{A}/\mu\text{s}$ | —    | 0.42 | —    | $\mu\text{C}$ |



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